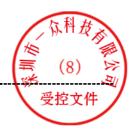
LCD Module Product Specification

		: APPRO	OVAL FOR SPECIFICATION
For Customer :		: APPRO	VAL FOR SAMPLE
Module No.: TST2		<u>50</u>	
Approved by		Comment	
15			
Team Source Display	:		
Presented by	Reviewed	by	Organized by
Buyer		VZ	INAVEN

This module uses ROHS material



REVISION RECORD

REV NO.	REV DATE	CONTENTS	REMARKS
V1	2015-09-20	First Release	Preliminary
		10/	

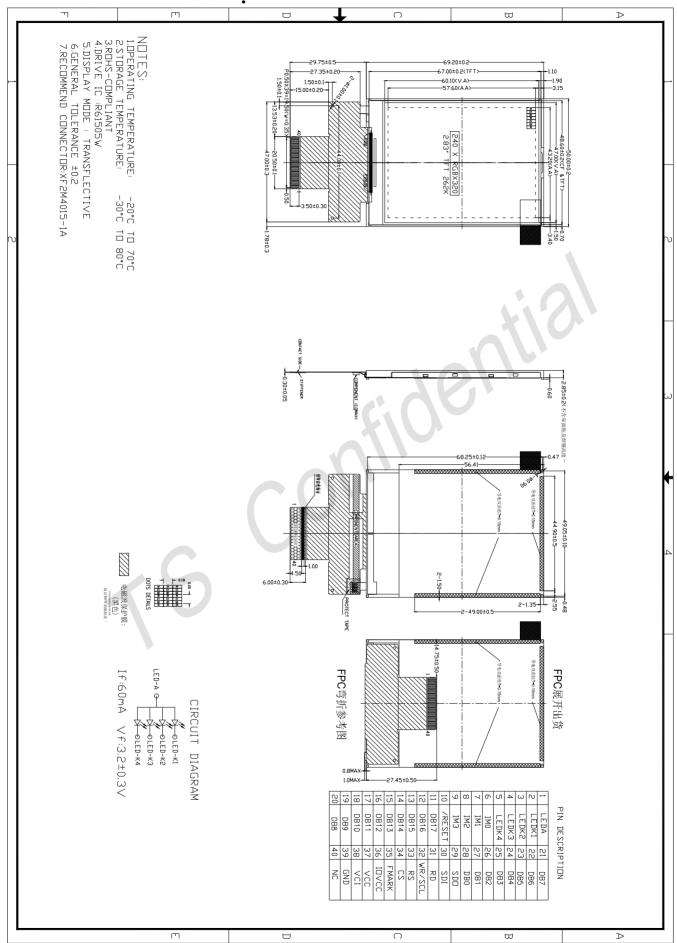
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■ GENERAL INFORMATION

Item of general information	Contents	Unit
LCD type	TFT/TRANSFLECTIVE	/
Recommended Viewing Direction	3:00	O' Clock
Module area ($W \times H \times T$)	50.00×69.20×2.85	mm^3
Viewing area (W×H)	47.00×60.10	mm ²
Active area (W×H)	43.20×57.60	mm ²
Number of Dots	240RGB×320	/
Pixel pitch (W × H)	0.180×0.180	mm ²
Driver IC	R61505W	/
Interface Type	Parallel /Serial interface	/
Input voltage	3.3	V
Module Power consumption	225	mw
Backlight Type	LED	/

■ EXTERNAL DIMENSIONS



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■ ABSOLUTE MAXIMUM RATINGS

Parameter of absolute maximum ratings	Symbol	Min	Max	Unit
Supply voltage for logic	VCC/VCI/IOVCC	-0.3	4.6	V
Input voltage	VIN	-0.3	IOVCC+0.3	V
Operating temperature	Тор	-20	70	°C
Storage temperature	TST	-30	80	°C
Humidity	RH	-	90%(Max60 °C)	RH

■ ELECTRICAL CHARACTERISTICS

DC CHARACTERISTICS

Parameter of DC characteristics	Symbol	Min	Тур	Max	Unit
Supply voltage for logic	VCC/VCI	2.5	-	3.3	V
I/O power supply	IOVCC	1.65	- 1	3.3	V
Input Current	Idd	-	7.8	11.7	mA
Input voltage 'H' level	VIH	0.8IOVCC		IOVCC	V
Input voltage 'L' level	VIL	-0.3	-	0.2IOVCC	V
Output voltage 'H' level	VOH	0.8IOVCC	-	-	V
Output voltage 'L' level	VOL	-	-	0.2IOVCC	V

■ BACKLIGHT CHARACTERISTICS

Item of backlight characteristics	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward voltage	Vf	2.9	3.2	3.4	V	If=60mA
Luminance	Lv	3500	3900	4300	cd/m ²	Ta=25 ℃
Number of LED	-	-	4	-	Piece	-
Connection mode	P	-	Parallel	-	1	-

Using condition: constant current driving method If=60mA(+/-10%).

■ ELECTRO-OPTICAL CHARACTERISTICS

Item of electro-optical characteristics	Symbol	Condition	Min	Тур	Max	Unit	Remark	Note
Response time	Tr+ Tf		-	25	40	ms	Fig.1	4
Contrast ratio	Cr	θ=0°	34	67	-		FIG 2.	1
Luminance uniformity	δ WHITE	Ø=0° Ta=25℃	70	85	-	%	FIG 2.	3
Surface Luminance	Lv	1a-23 C	112	150	-	cd/m ²	FIG 2.	2
		Ø = 90°	30	45	-	deg	FIG 3.	
Viewing angle	0	Ø = 270°	10	20	-	deg	FIG 3.	6
range	θ	Ø = 0°	40	50	-	deg	FIG 3.	0
		Ø = 180°	20	30	-	deg	FIG 3.	
NTSC ratio			-	40	- 🛕	%	-	-
	Red x		0.5087	0.5587	0.6087	-		
	Red y		0.2934	0.3434	0.3934	-		
	Green x	θ=0°	0.2805	0.3305	0.3805]	
CIE (x, y)	Green y	Ø=0°	0.5208	0.5708	0.6208	-	FIG 2.	5
chromaticity	Blue x	Ta=25°C	0.1157	0.1657	0.2157	-	FIG 2. 3	
	Blue y	1 a-23 C	0.0930	0.1430	0.1930	-		
	White x		0.2447	0.3047	0.3647	-		
	White y		0.2765	0.3365	0.3965	-		

Note1. Contrast Ratio(CR) is defined mathematically by the following formula. For more information see FIG 2.:

Contrast Ratio = Average Surface Luminance with all white pixels (P 1,P2, P 3,P4, P5)

Average Surface Luminance with all black pixels (P1, P2, P 3,P4, P5)

Note2. Surface luminance is the LCD surface from the surface with all pixels displaying white. For more information see FIG 2.

Lv = Average Surface Luminance with all white pixels (P1, P2, P3, P4, P5)

Note3. The uniformity in surface luminance (δ WHITE) is determined by measuring luminance at each test position 1 through 5, and then dividing the maximum luminance of 5 points luminance by minimum luminance of 5 points luminance. For more information see FIG 2.

$\delta \text{ WHITE} = \frac{\text{Minimum Surface Luminance with all white pixels } (P_1, P_2, P_3, P_4, P_5)}{\text{Maximum Surface Luminance with all white pixels } (P_1, P_2, P_3, P_4, P_5)}$

- Note4. Response time is the time required for the display to transition from White to black(Rise Time, Tr) and from black to white(Decay Time, Tf). For additional information see FIG 1..
- Note5. CIE (x, y) chromaticity ,The x,y value is determined by screen active area position 5. For more information see FIG 2.
- Note6. Viewing angle is the angle at which the contrast ratio is greater than 2. For TFT module the conrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG 3.
- Note7. For Viewing angle and response time testing, the testing data is base on Autronic-Melchers, s ConoScope. Series Instruments. For contrast ratio, Surface Luminance, Luminance uniformity and CIE, the testing data is base on TOPCON's BM-5 photo detector.
- Note8. For TFT transmissive module, Gray scale reverse occurs in the direction of panel viewing angle.

FIG.1. The definition of Response Time

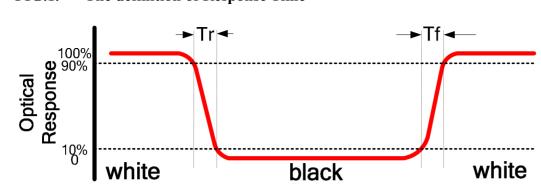


FIG.2. Measuring method for Contrast ratio, surface luminance, Luminance uniformity, CIE (x, y) chromaticity

A: 5 mm B: 5 mm

H,V: Active Area

Light spot size ∅=5mm, 500mm distance from the

LCD surface to detector lens

measurement instrument is TOPCON's luminance

meter BM-5

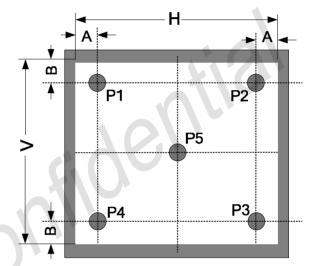
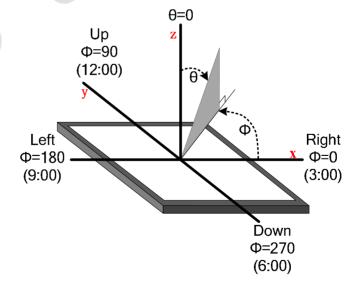


FIG.3. The definition of viewing angle



■ INTERFACE DESCRIPTION

Interface NO.	Symbol	I/O or connect to	Description	When not in use
1	LEDA	LED driver	LED ANODE	open
2	LEDK1	LED driver	LED CATHODE	open
3	LEDK2	LED driver	LED CATHODE	open
4	LEDK3	LED driver	LED CATHODE	open
5	LEDK4	LED driver	LED CATHODE	open
6	IM0		1.01.4	
7	IM1] T	Interface mode Select.	
8	IM2	I	Refer to NOTE 1	-
9	IM3			
10	/RESET	I Host processor	Reset signal. The R61505W is initialized when this signal is at low level. Make sure to execute a power-on reset when turning on power supply (Amplitude: IOVCC-GND).	-
11	DB17			
12	DB16			
13	DB15			
14	DB14			
15	DB13		18-bit bi-directional data bus. If not used, please fix this	
16	DB12		pin at GND level.	
17	DB11		8-bit I/F: DB[17:10] are used.	
18	DB10	7/0	9-bit I/F: DB[17:9] are used.	
19	DB9	I/O	16-bit I/F: DB[17:10] and DB[8:1] are used.	IOVCC or
20	DB8	Host	18-bit I/F: DB[17:0] are used.	GND
21	DB7	processor	18-bit parallel bi-directional data bus for RGB interface	
22	DB6		operation (Amplitude: IOVCC-GND).	
23	DB5		16-bit I/F: DB[17:13] and DB[11:1] are used.	
24	DB4		18-bit I/F: DB[17:13] and DB[11:1] are used.	
25	DB3		10-bit 1/1 : DD[17.0] are used.	
26	DB2			
27	DB1			
28	DB0	1		
29	SDO	O Host processor	Serial data output (SDO) pin in serial interface operation. The data is outputted on the falling edge of the SCL signal.Amplitude: IOVCC-GND	open
30	SDI	I Host processor	SPI interface input pin. The data is latched on the rising edge of the SCL signal.	-
31	RD	I Host processor	Read strobe signal in 80-system bus interface operation and enables read operation when RDX is low. Amplitude: IOVCC-GND	IOVCC
32	WR/SCL	I Host processor	Write strobe signal in 80-system bus interface operation and enables write operation when WRX is low. Synchronous clock signal (SCL) in serial interface operation. Amplitude: IOVCC-GND	IOVCC

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		Т	A register galact gional		
		1	A register select signal.		
33	RS	Host	Low: select an index or status register	IOVCC	
		processor	High: select a control register		
		I	Chip select signal. Amplitude: IOVCC-GND		
34	CS	Host	Low: the R61505W is selected and accessible	IOVCC	
		processor	High: the R61505W is not selected and not accessible.		
		O	Frame head pulse signal, which is used when writing		
35	FMARK	Host	data to the internal frame memory. (Amplitude:	open	
		processor	IOVCC-GND).		
36	IOVCC	Power	Power supply for digital IO.Connect to an external		
30	10000	supply	power supply of $1.65 \sim 3.3$ V.	_	
37	VCC	Power	Davyar gunnly to internal logic regulator circuit		
37	VCC	supply	Power supply to internal logic regulator circuit.		
20	VCI	Power	Power supply for analog circuitConnect to an external		
38	VCI	supply	power supply of $2.5 \sim 3.3$ V.	_	
20	CND	Power	Lutamatta di CND		
39 GND		supply	Internal logic GND.	-	
40	NC	NC	NC	-	

NOTE 1:

Select a mode to interface to host processor. (Amplitude: IOVCC ~ GND)

IM3	IM2	IM1	IMO	Interface Mode	DB Pin	Colors
0	0	0	0	Setting disabled	1.0	150
0	0	0	1	Setting disabled	922	028
0	0	1	0	80-system 16-bit interface	DB[17:10], DB[8:1]	262,144 see Note 1
0	0	1	1	80-system 8-bit interface	DB[17:10]	262,144 see Note 2
0	1	0	0	Clock synchronous serial interface	14	65,536
0	1	0	1	Setting disabled		
0	1	1	0	Setting disabled	455	679
0	1	1	1	Setting disabled -		246
1	0	0	0	Setting disabled	绿	4 7 81
1	0	0	1	Setting disabled	#	5233
1	0	1	0	80-system 18-bit interface	DB[17:0]	262,144
1	0	1	1	80-system 9-bit interface	DB[17:9]	262,144
1	1	0	0	Setting disabled	\$ \	1
1	1	0	1	Setting disabled -		0230
1	1	1	0	Setting disabled -		9 - 33
1	1	1	1	Setting disabled	绿	2 7 21

Notes: 1. 65,536 colors in one transfer mode

2. 65,536 colors in two transfers mode

■ REFERENCE APPLICATION CIRCUIT

Please consult our technical department for detail information.

■ RELIABILITY TEST CONDITIONS

No.	Test Item	Test Condition	Inspection after test
1	High Temperature Storage	80±2°C/200 hours	
2	Low Temperature Storage	-30 ± 2 °C/200 hours	
3	High Temperature Operating	70 ± 2 °C/120 hours	Inspection of an
4	Low Temperature Operating	-20 ± 2 °C/120 hours	Inspection after 2~4hours storage at
5	Temperature Cycle storage	$-20\pm2^{\circ}\text{C} \sim 25 \sim 70\pm2^{\circ}\text{C} \times 10 \text{ cycles}$ (30min.) (5min.) (30min.)	room temperature, the sample shall be free from
6	Damp proof Test operating	$50^{\circ}\text{C} \pm 5^{\circ}\text{C} \times 90\%\text{RH}/120 \text{ hours}$	defects:
7	Vibration Test	Frequency: 10Hz~55Hz~10Hz Amplitude: 1.5mm, X, Y, Z direction for total 3hours (Packing condition)	1.Air bubble in the LCD; 2.Sealleak; 3.Non-display; 4.missing segments;
8	Dropping test	Drop to the ground from 1m height, one time, every side of carton. (Packing condition)	5.Glass crack;6.Current Idd is twice higher than initial value.
9	ESD test	Voltage:±8KV R: 330Ω C: 150pF Air discharge, 10time	

Remark

- 1. The test samples should be applied to only one test item.
- 2. Sample size for each test item is $5\sim10$ pcs.
- 3. For Damp Proof Test, Pure water(Resistance \geq 10M Ω) should be used.
- 4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.
- 5.EL evaluation should be excepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has
- 6. Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

■ INSPECTION CRITERION

This specification is made to be used as the standard acceptance/rejection criteria for Normal LCM Products from Team Source Display.

1 Sample plan

Sampling plan according to GB/T2828.1-2003/ISO 2859-1: 1999 and ANSI/ASQC Z1.4-1993, normal level 2 and based on:

Major defect: AQL 0.65 Minor defect: AQL 1.5

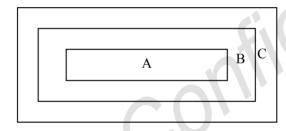
2. Inspection condition

•Viewing distance for cosmetic inspection is about 30cm with bare eyes, and under an environment of 20~40W light intensity, all directions for inspecting the sample should be within 45°against perpendicular line. (Normal temperature 20~25°C and normal humidity 60±15%RH).

Driving voltage

The Vop value from which the most optimal contrast can be obtained near the specified Vop in the specification (Within ± 0.5 V of the typical value at 25°C.).

3. Definition of inspection zone in LCD.



Zone A: character/Digit area

Zone B: viewing area except Zone A (ZoneA+ZoneB=minimum Viewing area)

Zone C: Outside viewing area (invisible area after assembly in customer's product)

Fig.1 Inspection zones in an LCD.

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble for quality and assembly of customer's product.

4.Inspection Standard

4.1 Major Defect

Item No	Items to be inspected	Inspection Standard	Classification of defects
4.1.1	All functional defects	 No display Display abnormally Missing vertical, horizontal segment Short circuit Back-light no lighting, flickering and abnormal lighting. 	
4.1.2	Missing	Missing component	Major
4.1.3	Outline dimension	Overall outline dimension beyond the drawing is not allowed.	

4.2 Cosmetic Defect

4.2.1 Module Cosmetic Criteria

No.	Item	Judgement Criterion	Partition
1	Difference in Spec.	None allowed	Major
2	Pattern peeling	No substrate pattern peeling and floating	Major
3	Soldering defects	No soldering missing No soldering bridge No cold soldering	Major Major Minor
4	Resist flaw on Printed Circuit Boards	visible copper foil (Ø0.5mm or more) on substrate pattern	Minor
5	Accretion of metallic Foreign matter	No accretion of metallic foreign matters (Not exceed Ø0.2mm)	Minor Minor
6	Stain	No stain to spoil cosmetic badly	Minor
7	Plate discoloring	No plate fading, rusting and discoloring	Minor
8	Solder amount 1. Lead parts	a. Soldering side of PCB Solder to form a 'Filet' all around the lead. Solder should not hide the lead form perfectly. (too much) b. Components side (In case of 'Through Hole PCB') Solder to reach the Components side of PCB.	Minor
	2. Flat packages	Either 'Toe' (A) or 'Seal' (B) of the lead to be covered by 'Filet'. Lead form to be assume over solder.	Minor
	3. Chips	$(3/2) H \ge h \ge (1/2) H$	Minor

a solder ball to become dislodged.	9	Solder ba splash	all/Solder	the conductor or solder pad h≥0.13mn The diameter of solder ball d≤0.15mm. b. The quantity of solder balls or solder Splashes isn't beyond 5 in 600 mm². c. Solder balls/Solder splashes do not violate minimum electrical clearance. d. Solder balls/Solder splashes must be entrapped/encapsulated Or attached to the metal surface. NOTE: Entrapped/encapsulated/attached is intended to mean that normal service environment of the product will not cause	Minor Minor Major Minor
------------------------------------	---	---------------------	------------	--	----------------------------------

4.2.2Cosmetic Criteria (Non-Operating)

No.	Defect	Judgment Criterion		
1	Spots	In accordance with Screen Cosmetic Criteria (Operating) No.1.		
2	Lines	In accordance with Screen Cos	smetic Criteria (Operating) No.2.	Minor
3	Bubbles in polarizer			Minor
		Size : d mm	Acceptable Qty in active area	
		d ≤ 0.3	Disregard	
		$0.3 < d \le 1.0$	3	
		$1.0 < d \le 1.5$	1	
		1.5 < d	0	
4	Scratch	In accordance with spots and lines operating cosmetic criteria. When the		
		light reflects on the panel surface, the scratches are not to be remarkable.		
5	Allowable density	Above defects should be separated more than 30mm each other.		
6	Coloration	Not to be noticeable coloration in the viewing area of the LCD panels.		
		Back-lit type should be judged with back-lit on state only.		
7	Contamination	Not to be noticeable.		

4.2.3 Cosmetic Criteria (Operating)

No.	Defect				Partition
1	Spots A) Clear			Minor	
		Lcd size	Size : d mm	Acceptable Qty in active area	
		Ded Size	d≤0.1	Disregard	
		Lcd size≤8.0'	$0.1 < d \le 0.2$	6	
			$0.2 < d \le 0.3$	2	
			0.3 < d	0	
			d ≤0.1	Disregard	
		Lcd size>8.0'	0.1 < d < 0.3	10	
			0.3 < d < 0.5	5	
			0.5 < d	0	
		Note: Including pin holes and defective dots which must be within one pixel size; Total defective point shall not exceed 6 pcs no more than 8 inch LCD and 10PCS for more than 8 inch LCD. B) Unclear			
		Lcd size	Size : d mm	Acceptable Qty in active area	
			d≤0.2	Disregard	
		Lcd size≤	0.2 <d≤0.5< td=""><td></td><td></td></d≤0.5<>		
		8.0'	0.5 <d≤0.7< td=""><td>7 2</td><td></td></d≤0.7<>	7 2	
			0.7 <d< td=""><td>0</td><td></td></d<>	0	
			d≤0.2	Disregard	
			0.2 <d≤0.5< td=""><td>5 10</td><td></td></d≤0.5<>	5 10	
		Lcd size $> 8.0'$	0.5 <d≤0.7< td=""><td>7 3</td><td></td></d≤0.7<>	7 3	
			0.7 <d\le 1.0<="" td=""><td>1</td><td></td></d\le>	1	
			1.0< d	0	
2 Lines		Note: Total defective poinch LCD and 10PCS for n		exceed 6 pcs for no more than 8	
		A) Clear			Minor
		$\begin{array}{ c c c c c c c c c c c c c c c c c c c$			
		2.0 (6)		See No. 1	
		0.02	05	<u> </u>	
		0.02 0	.05	0.1	
		Note: () - Acceptable (L) - Length (mm) W - Width (mm) \infty - Disregard B) Unclear L 10.0 \infty (6)	Qty in active an	rea (0)	
		20		Q XI	
		2.0		See No. 1	
		0.05	0.3	0.5 W	
		LCD operation voltage chan	ging .the defect size of the li	ine or dot are changed with the	

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3	Rubbing line	Not to be noticeable.	Minor
4	Allowable density	Above defects should be separated more than 10mm each other.	Minor
5	Rainbow	Not to be noticeable.	Minor
6	Dot size	To be 95% ~ 105% of the dot size (Typ.) in drawing. Partial defects of each dot (ex. pin-hole) should be treated as 'Spot'. (see <i>Screen Cosmetic Criteria (Operating) No.1</i>)	Minor
7	Uneven brightness (only back-lit type module)		Minor

Note:

- (1) Size : d = (long length + short length) / 2
- (2) The limit samples for each item have priority.
- (3) Complex defects are defined item by item, but if the numbers of defects are defined in above table, the total number should not exceed 10.
- (4) In case of 'concentration', even the spots or the lines of 'disregarded' size should not allowed. Following three situations should be treated as 'concentration'.
 - 7 or over defects in circle of Ø5mm.
 - 10 or over defects in circle of Ø10mm.
 - 20 or over defects in circle of Ø20mm.

■ PRECAUTIONS FOR USING LCD MODULES

1 Handing Precautions

- 1.1 The display panel is made of glass and polarizer. As glass is fragile. It tends to become or chipped during handling especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it or impact.
- 1.2 If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.
- 1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary. Do not touch the display with bare hands. This will stain the display area and degraded insulation between terminals (some cosmetics are determined to the polarizer).
- 1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass, tweezers, etc.). Do not put or attach anything on the display area to avoid leaving marks on it. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming in to contact with room temperature air.
- 1.5 If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents
 - Isopropyl alcohol
 - Ethyl alcohol

Do not scrub hard to avoid damaging the display surface.

- 1.6 Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.
 - Water
 - Ketone
 - Aromatic solvents

Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading. Avoid contact with oil and fats.

- 1.7 Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.
- 1.8 Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.
- 1.9 Do not attempt to disassemble or process the LCD module.
- 1.10 NC terminal should be open. Do not connect anything.
- 1.11 If the logic circuit power is off, do not apply the input signals.
- 1.12 Electro-Static Discharge Control, Since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - Before removing LCM from its packing case or incorporating it into a set, be sure the module and your body have the same electric potential. Be sure to ground the body when handling the LCD modules.
 - Tools required for assembling, such as soldering irons, must be properly grounded. Make certain the AC power source for the soldering iron does not leak. When using an electric screwdriver to attach LCM, the screwdriver should be of ground potentiality to minimize as much as possible any transmission of electromagnetic waves produced sparks coming from the commutator of the motor.
 - To reduce the amount of static electricity generated, do not conduct assembling

and other work under dry conditions. To reduce the generation of static electricity be careful that the air in the work is not too dry. A relative humidity of 50%-60% is recommended. As far as possible make the electric potential of your work clothes and that of the work bench the ground potential.

- The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.
- 1.13 Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.
 - Do not alter, modify or change the shape of the tab on the metal frame.
 - Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
 - Do not damage or modify the pattern writing on the printed circuit board.
 - Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector.
 - Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
 - Do not drop, bend or twist the LCM.

3 Storage Precautions

- 3.1 When storing the LCD modules, the following precaution are necessary.
 - 3.1.1 Store them in a sealed polyethylene bag. If properly sealed, there is no need for the desiccant.
 - 3.1.2 Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C, and keep the relative humidity between 40%RH and 60%RH.
 - 3.1.3 The polarizer surface should not come in contact with any other objects (We advise you to store them in the anti-static electricity container in which they were shipped).

3.2 Others

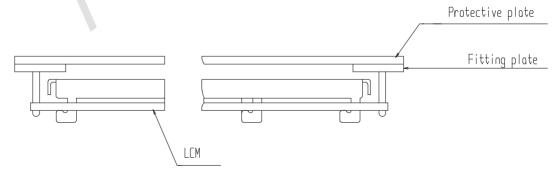
- 3.2.1 Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.
- 3.2.2 If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.
- 3.2.3 To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.
 - 3.2.3.1 Exposed area of the printed circuit board.
 - 3.2.3.2 Terminal electrode sections.

4 USING LCD MODULES

4.1 Installing LCD Modules

The hole in the printed circuit board is used to fix LCM as shown in the picture below. Attend to the following items when installing the LCM.

4.1.1 Cover the surface with a transparent protective plate to protect the polarizer and LC cell.



4.1.2 When assembling the LCM into other equipment, the spacer to the bit between the LCM and the fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be ± 0.1 mm.

4.3 Precaution for soldering the LCM

	Manual soldering	Machine drag soldering	Machine press soldering
No RoHS	290°C ~350°C.	330°C ~350°C.	300°C ~330°C.
Product	Time : 3-5S.	Speed: 15-17 mm/s.	Time : 3-6S.
Froduct			Press: 0.8~1.2Mpa
RoHS	340°C ~370°C.	350°C ~370°C.	330°C ~360°C.
Product	Time : 3-5S.	Speed: 15-17 mm/s.	Time : 3-6S.
Froduct			Press: 0.8~1.2Mpa

- 4.3.1 If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation (This does not apply in the case of a non-halogen type of flux). It is recommended that you protect the LCD surface with a cover during soldering to prevent any damage due to flux spatters.
- 4.3.2 When soldering the electroluminescent panel and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.
- 4.3.3 When remove the electroluminescent panel from the PC board, be sure the solder has completely melted, the soldered pad on the PC board could be damaged.

4.4 Precautions for Operation

- 4.4.1 Viewing angle varies with the change of liquid crystal driving voltage (VLCD). Adjust VLCD to show the best contrast.
- 4.4.2 It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life. An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- 4.4.3 Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operating temperature.
- 4.4.4 If the display area is pushed hard during operation, the display will become abnormal. However, it will return to normal if it is turned off and then back on.
- 4.4.5 A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit. Usage under the maximum operating temperature, 50%RH or less is required.
- 4.4.6 Input logic voltage before apply analog high voltage such as LCD driving voltage when power on. Remove analog high voltage before logic voltage when power off the module. Input each signal after the positive/negative voltage becomes stable.
- 4.4.7 Please keep the temperature within the specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off may occur with high temperature and high humidity.

4.5 Safety

- 4.5.1 It is recommended to crush damaged or unnecessary LCDs into pieces and wash them off with solvents such as acetone and ethanol, which should later be burned.
- 4.5.2 If any liquid leaks out of a damaged glass cell and comes in contact with the hands, wash off thoroughly with soap and water.

■ PACKING SPECIFICATION

Please consult our technical department for detail information.